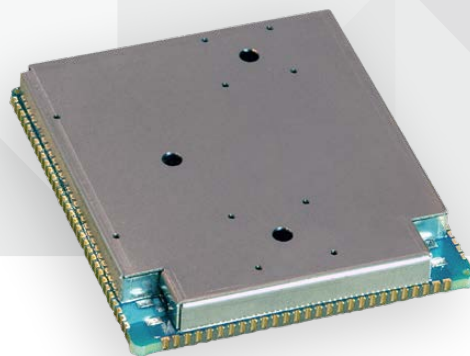




SECURE, CONNECTED
SYSTEM-ON-MODULE



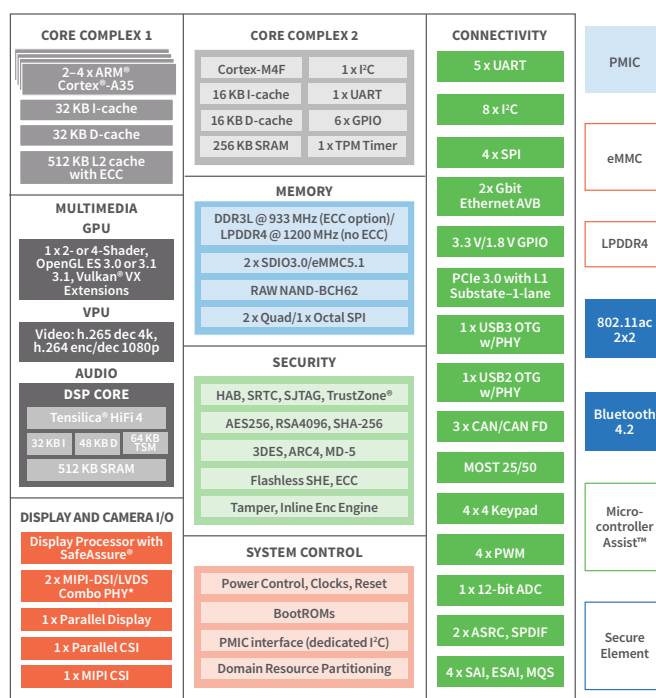
DIGI CONNECTCORE 8X

Intelligent and connected embedded system-on-module based on the NXP i.MX 8X; with scalable dual/quad-core performance for industrial IoT applications

Digi ConnectCore® 8X delivers a secure and cost-effective connected system-on-module platform that measures in at just 40 mm x 45 mm. The Digi SMTplus® surface mount form factor allows you to choose simplified design integration leveraging proven and easy-to-use edge-castellated SMT technology, or a versatile LGA option for ultimate design flexibility with access to virtually all interfaces.

Built on the NXP i.MX 8X application processor, the module is the intelligent communication engine for today's secure connected devices. ConnectCore 8X can help jump-start the development of streaming video/audio devices, voice control and general human-machine interface solutions. With a multitude of high performance interconnecting options, including 1x USB 3.0 port, dual Gigabit Ethernet, PCIe 3.0, and pre-certified dual-band 2x2 MU-MIMO WLAN, ConnectCore 8X is ideal for developing a wide range of embedded and IoT applications.

BLOCK DIAGRAM



BENEFITS

- Industrial i.MX 8X quad/dual-core SOM and SBC platform family
- Digi SMTplus® form factor (40 mm x 45 mm) for ultimate reliability and design freedom
- Power management with both hardware and software support for low-power designs
- Multi-display and camera capabilities with hardware acceleration
- Pre-certified dual-band 802.11a/b/g/n/ac 2x2 and Bluetooth® 4.2 connectivity
- Seamless cellular modem and Digi XBee3® integration
- Cloud and edge-compute services integration
- Built-in device security with Digi TrustFence®
- Yocto Project Linux and Android support

RELATED PRODUCTS



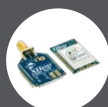
ConnectCore® 6UL



ConnectCore® 6+



ConnectCore® 8X SBC PRO



Digi XBee® Modules



ConnectCore® 8X Kits

SPECIFICATIONS	Digi ConnectCore® 8X
APPLICATION PROCESSOR	NXP i.MX8QuadXPlus • 4x Cortex-A35 cores @ 1.0 GHz • 1x Cortex-M4F @ 266 MHz core for real-time processing • 1x Tensilica® Hi-Fi 4 DSP
MEMORY	Up to 64 GB eMMC, up to 4 GB of LPDDR4
PMIC	NXP PF8100
GRAPHICS	Multi-stream-capable HD video engine with H.265 (4Kp30), H.264 (1080p60), VP6/VP8 (1080p60), MPEG-2 (1080p60), MPEG4 (1080p), RealVideo (1080p) decode and H.264 (1080p30) encode; 3D video playback in HD in high-performance families; Superior 3D graphics performance with up to four shaders
SECURITY	Digi TrustFence®, TRNG, TrustZone, ciphers, security control, secure RTC, secure JTAG, eFuses (OTP)
PERIPHERALS/ INTERFACES	1x SD 3.0 card interface handles SD/SDIO/MMC protocols (1x additional one reserved on the SOM for supporting eMMC) 5x UARTs (4x UARTs from Cortex-A35 core, 1x UART from Cortex-M4), S/PDIF Tx/Rx 8x I ² C (4x I ² C high-speed DMA support 4x I ² C low-speed no DMA support) 4x SPI, ESAI, 4x I ² S/SSI, 3x FlexCAN, MLB150 + DTCP, USB 3.0 OTG with PHY, USB 2.0 OTG with PHY 4x PWM, GPIO, Keypad, PCIe 3.0 (x1 lane), 2x MIPI DSI/LVDS, MIPI CSI, 8/10-bit CSI 24-bit RGB, RTC, Watchdog, Timers, JTAG
ETHERNET	2x 10/100/1000M Ethernet + AVB
WI-FI	802.11a/b/g/n/ac: 2.412 - 2.484 GHz, 4.900 - 5.850 GHz 802.11b: 1, 2, 5.5, 11 Mbps (17 dBm typical ±2 dBm) 802.11a/g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps (15 dBm typical ±2 dBm) 802.11n: 15, 30, 45, 60, 90, 120, 135, 150 Mbps (12 dBm typical ±2 dBm) HT40, MCS 0-7 802.11ac: 15, 30, 45, 60, 90, 120, 135, 150, 180, 200 Mbps (10 dBm typical ±2 dBm) HT40, MCS 0-9 Note: All data rates provided above are for 1x spatial stream (double the data rate for 2x spatial streams) Security: WEP, WPA-PSK/WPA2 personal, WPA/WPA2 enterprise, 802.11i, access point mode (up to 10 clients), Wi-Fi Direct Industry certifications: Wi-Fi Alliance Logo Certification Ready, CCXv4 ASD Ready
BLUETOOTH	Bluetooth 4.2
ON-MODULE MICROCONTROLLER ASSIST	Digi Microcontroller Assist™ • Independent Cortex-M0+ microcontroller subsystem • Supporting ultra-low power modes @ <3µA
OPERATING TEMPERATURE	Industrial: -40° C to 85° C (-40° F to 185° F), depending on use case and enclosure/system design Commercial: 0° C to 70° C (32° F to 158° F)
STORAGE TEMPERATURE	-50° C to 125° C (-58° F to 257° F)
RELATIVE HUMIDITY	5% to 90% (non-condensing)
ALTITUDE	3,658 meters (12,000 feet)
RADIO APPROVALS	US, Canada, EU, Japan, Australia/New Zealand
EMISSIONS/ IMMUNITY/ SAFETY	FCC Part 15 Class B, EN 55022 Class B, EN 61000-3-2, EN 61000-3-3, ICES- 003 Class B, VCCI Class II, AS 3548, FCC Part 15 Subpart C Section 15.247, IC (Industry Canada), RSS-210 Issue 5 Section 6.2.2(o), EN 300 328, EN 301 489-17, EN 55024, EN 301 489-3
DESIGN VERIFICATION	Temperature: IEC 60068-2-1, IEC 60068-2-2, IEC 60068-2-78 Vibration/Shock: IEC 60068-2-6, IEC 60068-2-64, IEC 60068-2-27, HALT
MECHANICAL DIMENSIONS	118 castellated vias, LGA-474, 1.27 mm pitch, fully shielded for radio emissions and thermal management (heat-spreading) 40 mm x 45 mm x 3.5 mm (1.6 in x 1.8 in x 0.1 in)
PRODUCT WARRANTY	3 years

PART NUMBERS	DESCRIPTION
DIGI CONNECTCORE 8X DEVELOPMENT KITS	
CC-WMX8-KIT	Digi ConnectCore 8X SBC PRO development kit: SBC PRO baseboard with ConnectCore 8X module, Pico-ITX (100 x 72 mm), Industrial Temp, 16 GB eMMC, 2 GB LPDDR4, Dual 1 Gbit Ethernet, 802.11a/b/g/n/ac 2x2, Bluetooth 4.2, XBee socket, cellular connectivity support via PCI Express Mini Card, SIM, microSD, USB Host, USB OTG, UART, DualCAN, SPI, I2C, LVDS, camera, antenna connector, battery connector, UART console cable, power supply and antennas, software support for Yocto Linux and Android, Kinetis Microcontroller Assist
DIGI CONNECTCORE 8X SBC PRO	
CC-SBP-WMX-JM8E	Digi ConnectCore 8X SBC PRO: i.MX8QuadXPlus, 1.0 GHz, -40° C to 85° C (-40° F to 185° F), 16 GB flash, 2 GB LPDDR4, 802.11a/b/g/n/ac 2x2, Bluetooth 4.2, dual Gigabit Ethernet
DIGI CONNECTCORE 8X SOMS	
CC-WMX-JP7D-ZN	Digi ConnectCore 8X SOM DualX 1.0 GHz, 8 GB eMMC, 1 GB LPDDR4, -40° C to 85° C (-40° F to 185° F), 802.11a/b/g/n/ac 2x2, Bluetooth 4.2
CC-WMX-JM8E-NN	Digi ConnectCore 8X SOM QuadXPlus 1.0 GHz, 16 GB eMMC, 2 GB LPDDR4, -40° C to 85° C (-40° F to 185° F), 802.11a/b/g/n/ac 2x2, Bluetooth 4.2
CC-MX-JM8D-ZN	Digi ConnectCore 8X SOM QuadXPlus 1.0 GHz, 8 GB eMMC, 2 GB LPDDR4, -40° C to 85° C (-40° F to 185° F)
CC-MX-JP6D-ZN	Digi ConnectCore8X SOM DualX 1.0 GHz, 8 GB eMMC, 512 Mb LPDDR4, -40° C to 85° C (-40° F to 185° F)
CC-MX-JP7D-ZN	Digi ConnectCore8X SOM DualX 1.0 GHz, 8 GB eMMC, 1 GB LPDDR4, -40° C to 85° C (-40° F to 185° F)

ACCESSORIES	DESCRIPTION
CC-ACC-LCDW-10	LCD application kit, including 10 in WXGA (1280x800) LCD panel with PCAP touch

